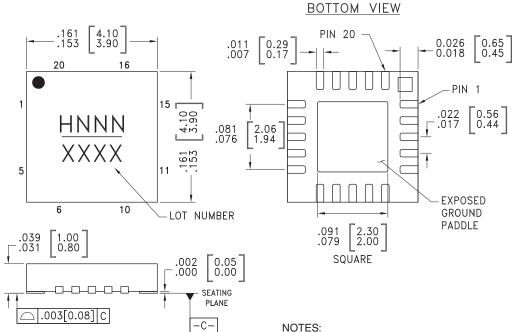


LP4B (E) - 4 x 4 mm QUAD FLATPACK NO-LEAD (QFN) PLASTIC PACKAGE



LP4B (E) Package



- 1. PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED
- PLASTIC SILICA AND SILICON IMPREGNATED.
- 2. LEAD AND GROUND PADDLE MATERIAL: COPPER ALLOY.
- 3. LEAD AND GROUND PADDLE PLATING: 100% MATTE TIN
- 4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 5. LEAD SPACING TOLERANCE IS NON-CUMULATIVE. 6. PAD BURR LENGTH SHALL BE 0.15mm MAX. PAD BURR HEIGHT SHALL BE 0.05mm MAX.
- 7. PACKAGE WARP SHALL NOT EXCEED 0.05mm
- 8. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking [3][4]
LP4B	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 [1]	HNNN XXXX
LP4BE	RoHS Compliant Mold Compound	100% matte Sn	MSL1 [2]	HNNN XXXX

- [1] Max peak reflow temperature of 235 $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX
- [4] 3-Digit part number NNN